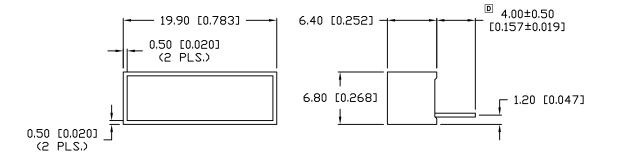
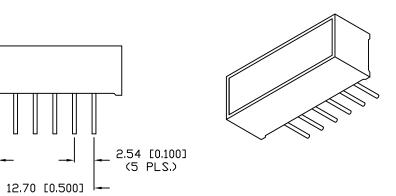
UNCONTROLLED DOCUMENT





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PART NUMBER SSB-IX620IW

| REV. | E.C.N. NUMBER AND REVISION COMMENTS | DATE |
|------|-------------------------------------|----------|
| Α | E.C.N. #10BRDR. & REDRAWN. | 7.10.98 |
| В | E.C.N. #10BRDR. & REDRAWN. | 6.20.01 |
| С | E.C.N. #11148. | 1.21.05 |
| D | E.C.N. #11859. | 05.02.13 |

| ELECTRO-OPTICAL C | HARACTERI | STICS TA=25°C | | $I_f = 20 \text{mA}$ | |
|--------------------|-----------|----------------|-----|----------------------|--------------|
| PARAMETER | MIN | TYP | MAX | UNITS | TEST COND |
| PEAK WAVELENGTH | | 635 | | nm | |
| FORWARD VOLTAGE | | 2.1 | 2.8 | v_f | |
| REVERSE VOLTAGE | 5.0 | | | V_r | Ir=100µA |
| AXIAL INTENSITY | | 15 | | mcd | $I_f = 20mA$ |
| VIEWING ANGLE | | 160 | | 2x theta | |
| EMITTED COLOR: | RED | | | | |
| EPOXY LENS FINISH: | MILKY \ | WHITE DIFFUSED |) | | |

LIMITS OF SAFE OPERATION AT 25°C PER CHIP

| PARAMETER | MAX | UNITS |
|--------------------------|-------------|------------|
| PEAK FORWARD CURRENT* | 150 | mA |
| STEADY CURRENT | 30 | mA |
| POWER DISSIPATION | 105 | mW |
| DERATE FROM 25°C | - 1.6 | mW/°C |
| OPERATING, STORAGE TEMP. | - 40 TO +85 | •C |
| SOLDERING TEMP. | + 260 | •C |
| 2.0mm FROM BODY | | 3 SEC. MAX |
| | | |

^{*} t<10µS



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*UNLESS OTHERWISE SPECIFIED TOLERANCES PER DECIMAL PRECISION ARE: X=±1 (±0.039), X.X=±0.5 (±0.020), X.XX=±0.25 (±0.010), X.XXX=±0.127 (±0.005). LEAD SIZE=±0.05 (±0.002), LEAD LENGTH=±0.75 (±0.030). MIN= +DECIMAL PRECISION MAX. = +0.00 (±0.005). LEAD SIZE=±0.05 (±0.002), LEAD SIZE=±0.05 (±0.003). MIN= +DECIMAL PRECISION MAX. = +0.00 (±0.003). MIN= +DECI

REV. PART NUMBER SSB-LX620IW 6mm x 20mm, 3 CHIP LIGHT BAR,

RED CHIPS, MILKY WHITE DIFFUSED, LEAD FREE.

0.50 [0.020]

(6 PLS.)

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OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.



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CHECKED BY: APPROVED BY: DATE:

10.4.95 PAGE: 1 OF 1 SCALE: N/A

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